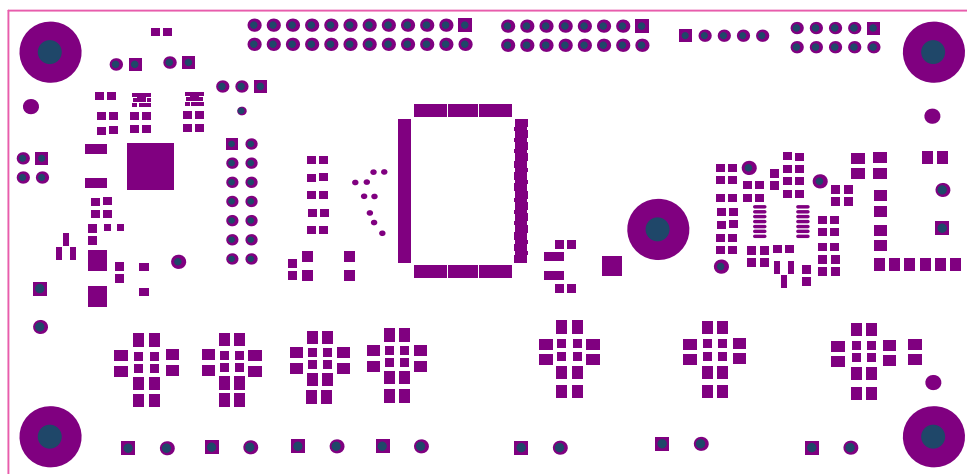
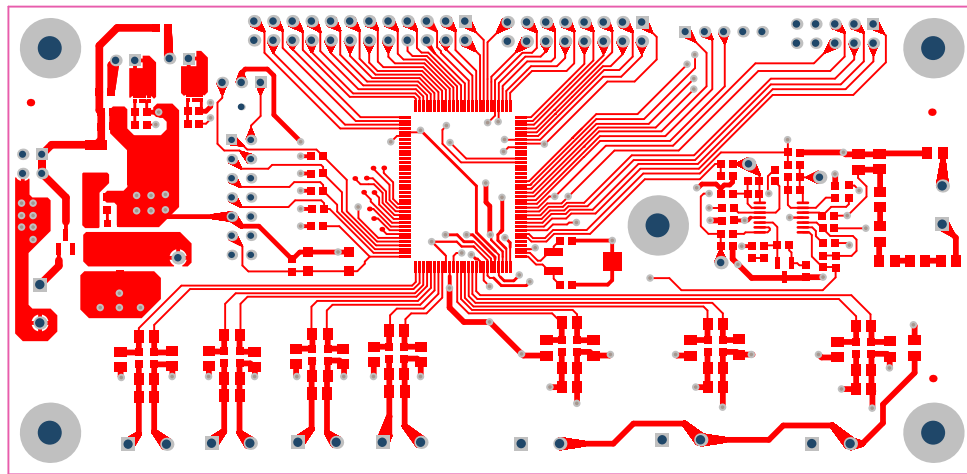


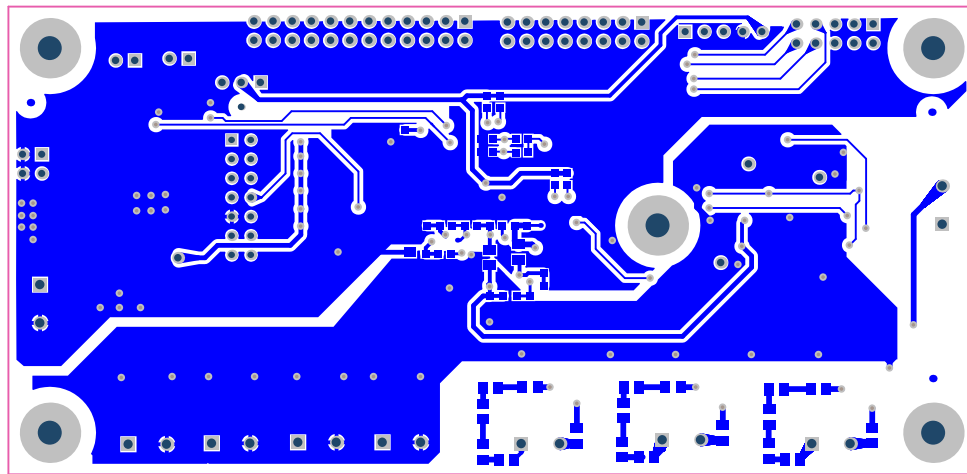
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/14/2014 2:33:23 PM	TEXAS INSTRUMENTS	



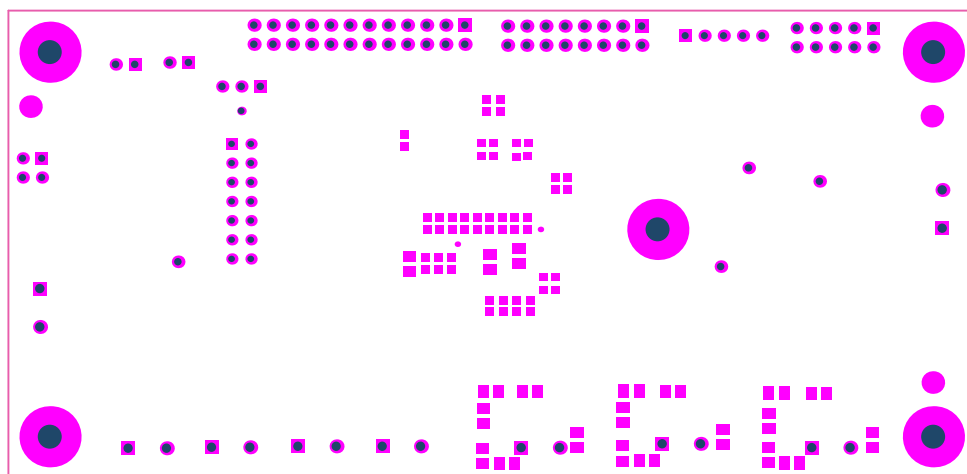
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/14/2014 2:33:23 PM	TEXAS INSTRUMENTS	



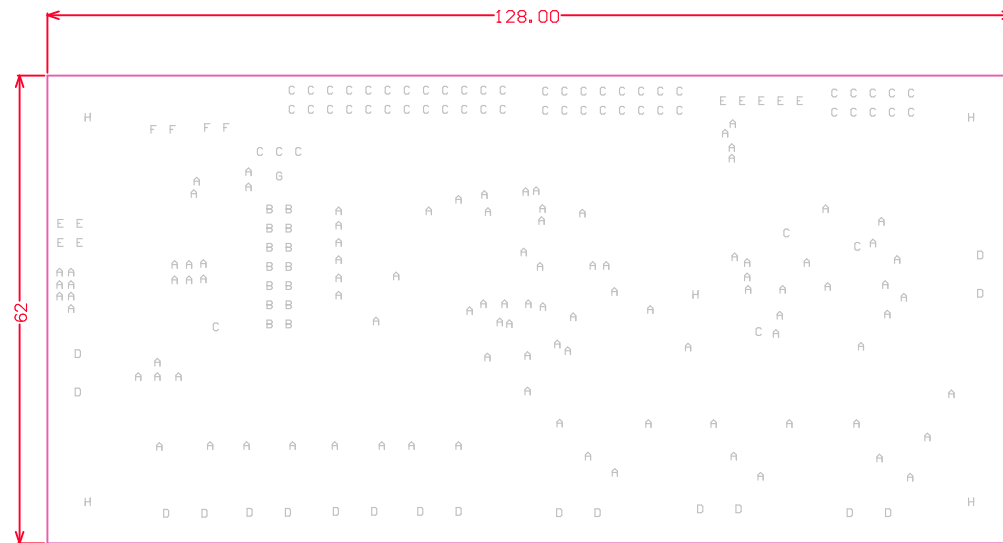
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
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PLOT NAME = Top Layer	GENERATED : 7/14/2014 2:33:24 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/14/2014 2:33:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/14/2014 2:33:25 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
A	100	20mil (0.508mm)	PTH	Round
G	1	35mil (0.889mm)	NPTH	Round
B	14	35mil (0.889mm)	PTH	Round
E	9	38mil (0.965mm)	PTH	Round
C	57	40mil (1.016mm)	PTH	Round
F	4	40.945mil (1.04mm)	PTH	Round
D	18	49.213mil (1.25mm)	PTH	Round
H	5	125.984mil (3.2mm)	PTH	Round
208 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00222	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/14/2014 2:33:25 PM	TEXAS INSTRUMENTS	

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